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(12) **United States Design Patent**
Nakabayashi et al.

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(54) **CIRCUIT BOARD MATERIAL**

(71) Applicants: **SUMITOMO ELECTRIC FINE POLYMER, INC.**, Sennan-gun, Osaka (JP); **SUMITOMO ELECTRIC PRINTED CIRCUITS, INC.**, Koka-shi, Shiga (JP)

(72) Inventors: **Makoto Nakabayashi**, Osaka (JP); **Masahiko Kouchi**, Koka (JP)

(73) Assignees: **SUMITOMO ELECTRIC FINE POLYMER, INC.**, Osaka (JP); **SUMITOMO ELECTRIC PRINTED CIRCUITS, INC.**, Shiga (JP)

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; D5/55, 58, 59; D25/103; 336/199, 200, 205, 206; 439/55, 64, 439/68, 77, 78; 174/250, 251, 255, 256, 174/257, 258, 259; 361/720, 748, 749, 750, 361/751, 760, 761, 762
See application file for complete search history.

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(Continued)

Primary Examiner — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — McDermott Will & Emery LLP

(57) **CLAIM**

The ornamental design for a circuit board material, as shown and described.

DESCRIPTION

The patent or application file contains at least one drawing executed in color. Copies of this patent or patent application publication with color drawing(s) will be provided by the Office upon request and payment of the necessary fee.

FIG. 1 is a front view of a circuit board material showing our new design;

FIG. 2 is a rear view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a left side view thereof;

FIG. 7 is an enlarged front view of the enclosed portion in FIG. 1;

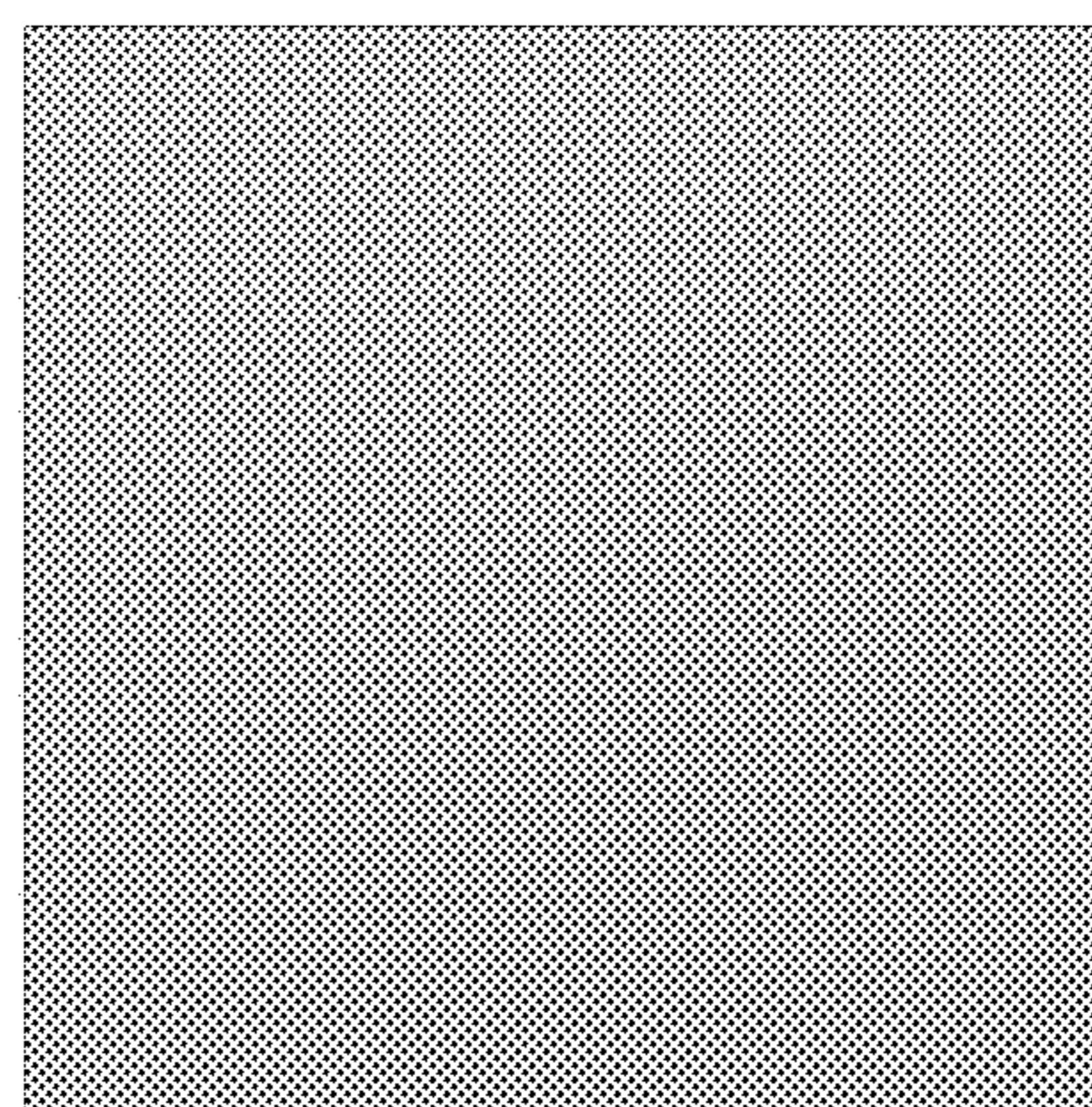
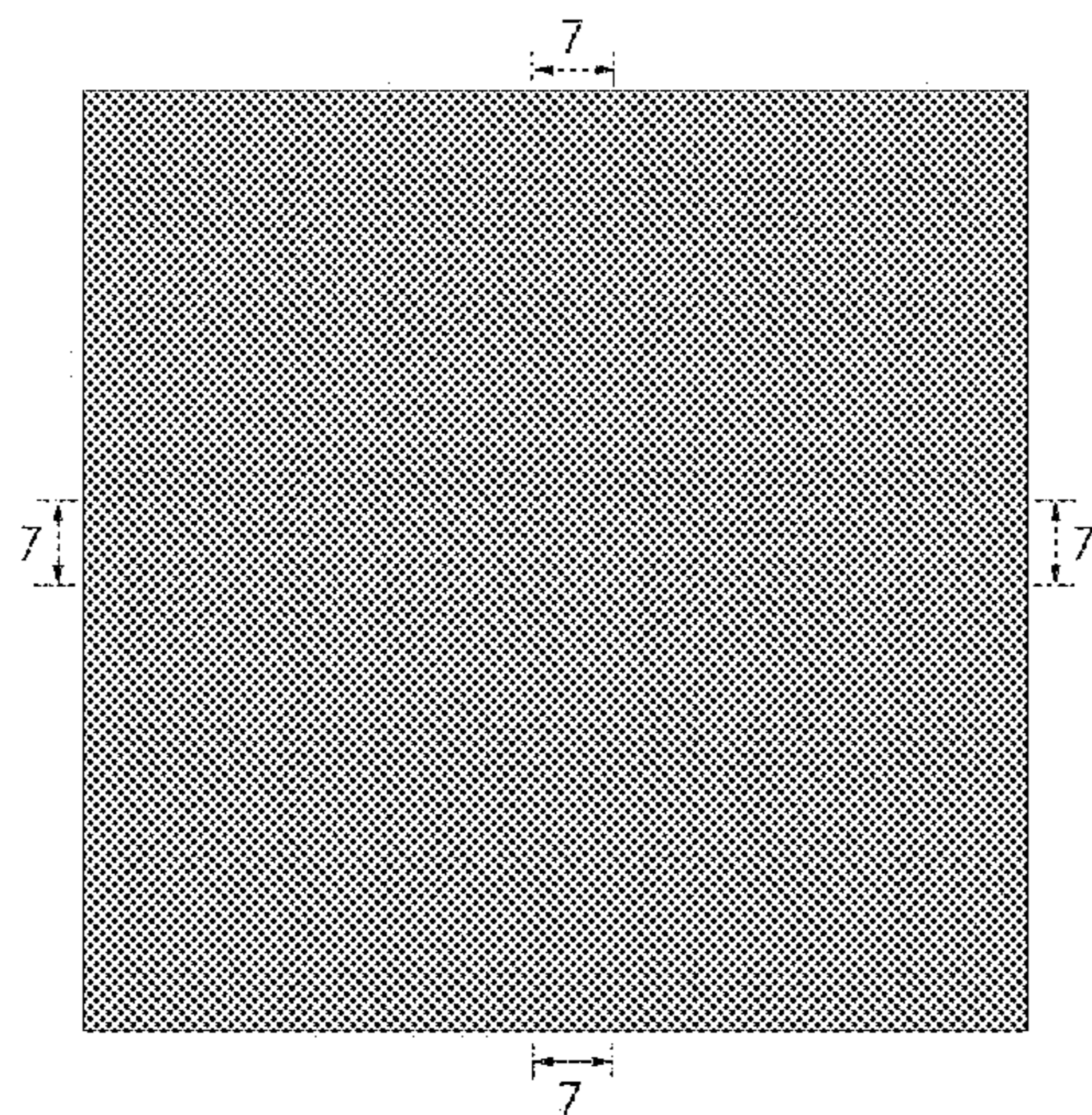
FIG. 8 is an enlarged right side view of the enclosed portion in FIG. 5; and,

FIG. 9 is an enlarged cross sectional view taken along line 9-9 in FIG. 7.

The upper layer of the circuit board material is a flat, transparent surface in which an underlying second layer showing a woven structure is visible through the first upper layer.

Dashed-dot-dashed broken lines define the boundary lines of the enlarged portions of the design in FIGS. 1, 5, and 7-9.

1 Claim, 7 Drawing Sheets
(4 of 7 Drawing Sheet(s) Filed in Color)



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FIG. 1

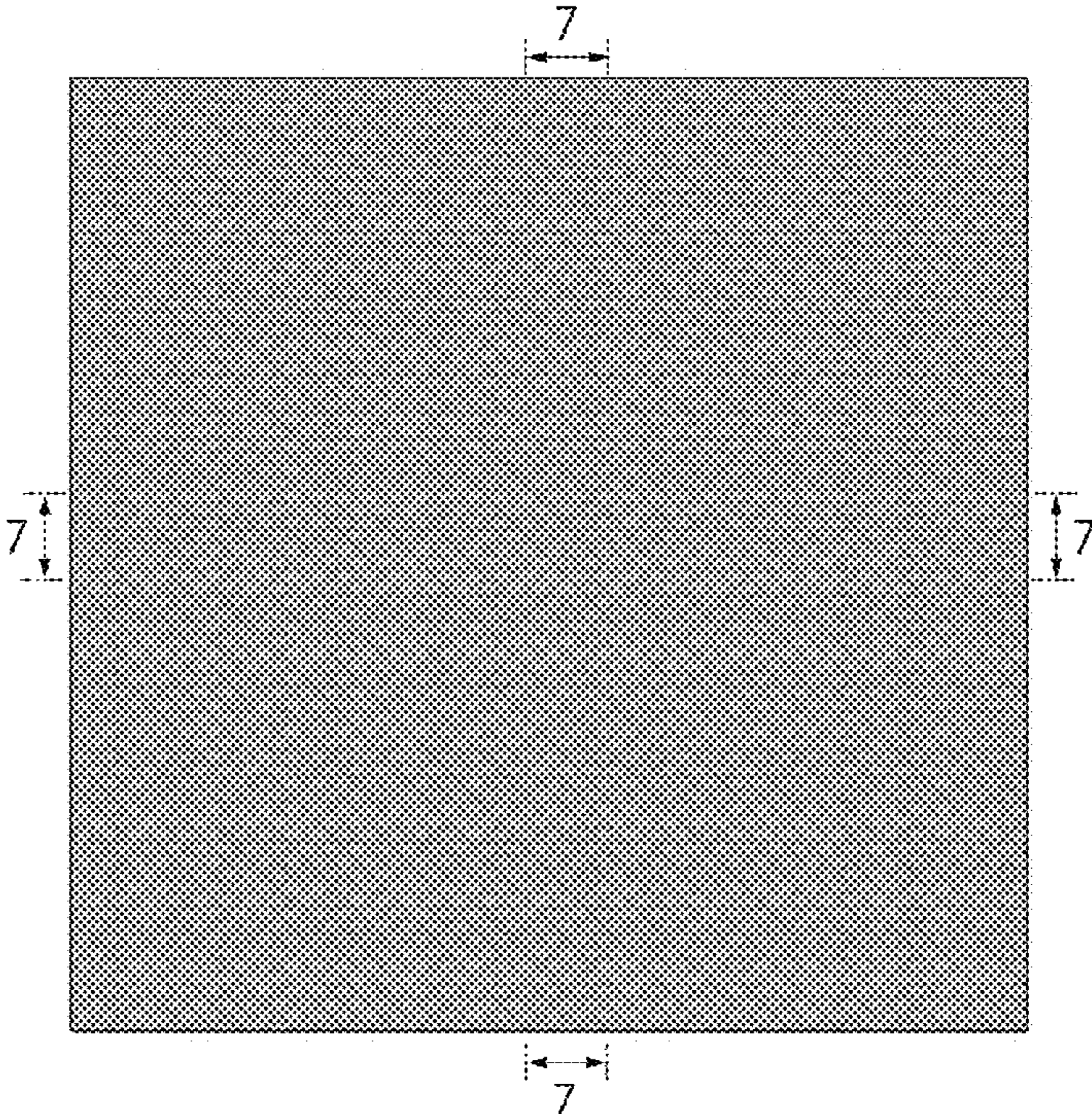


FIG. 2

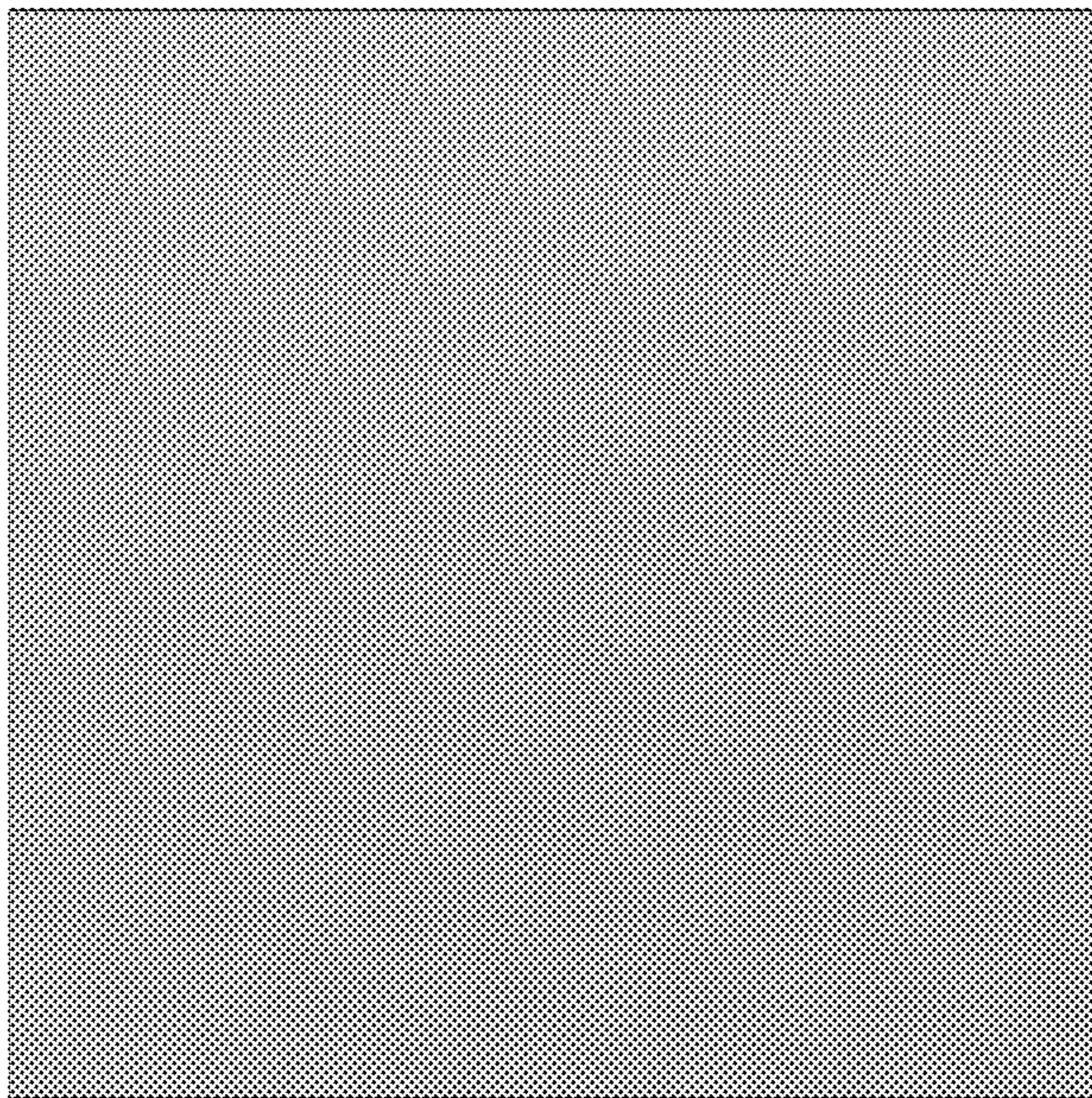


FIG. 3

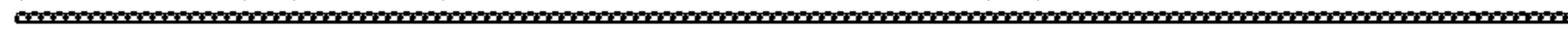


FIG. 4

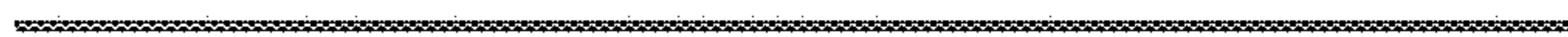


FIG. 5

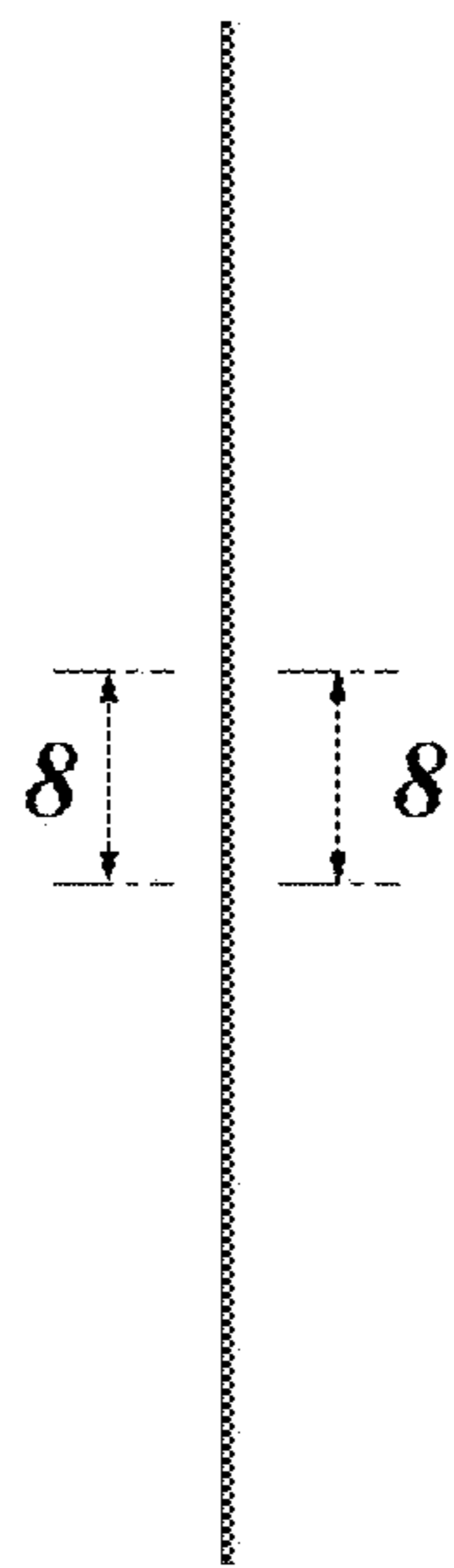


FIG. 6

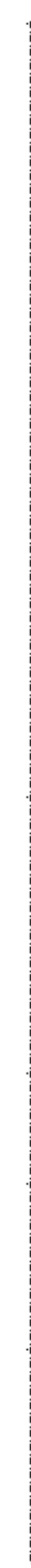


FIG. 7

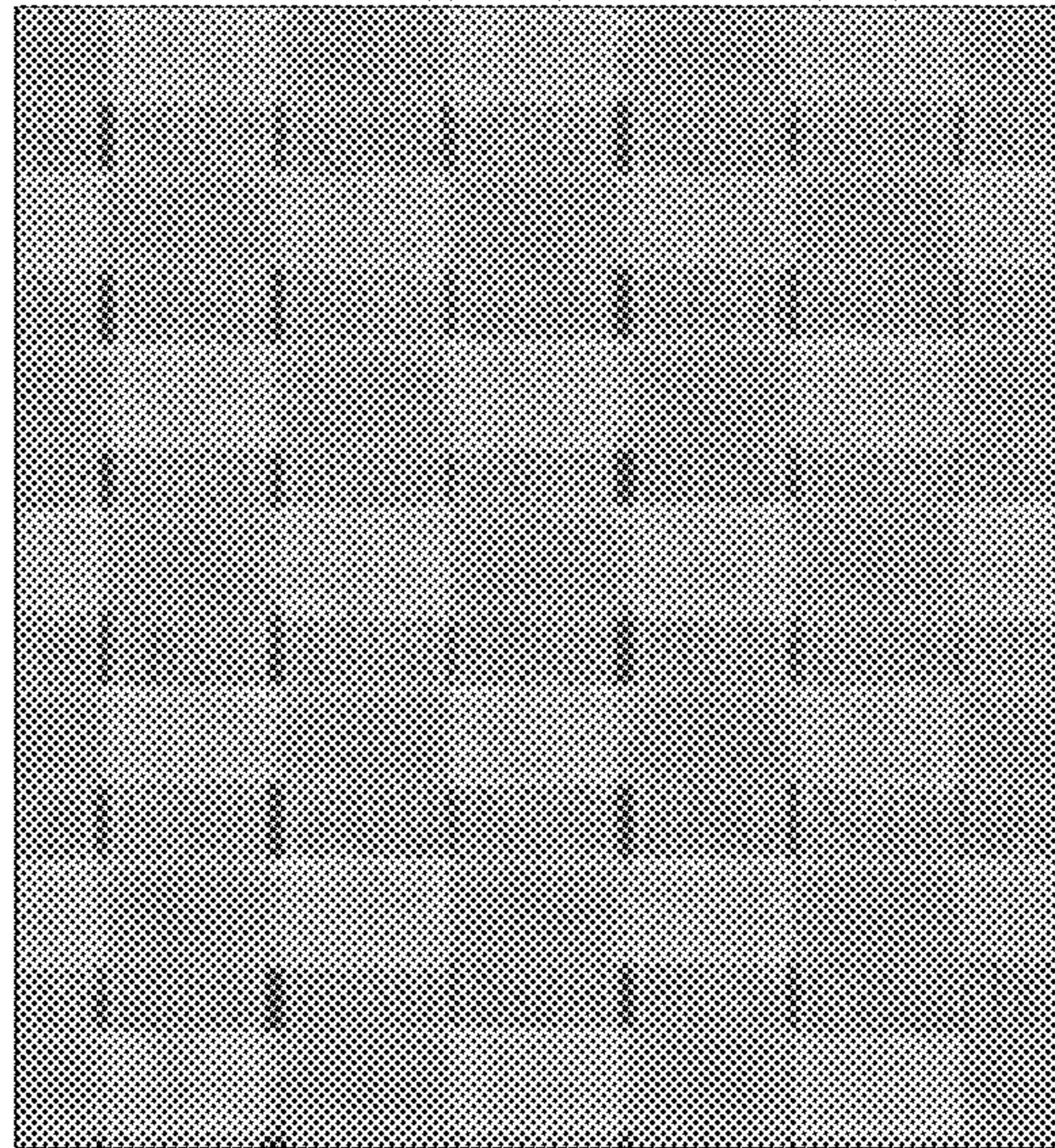


FIG. 8



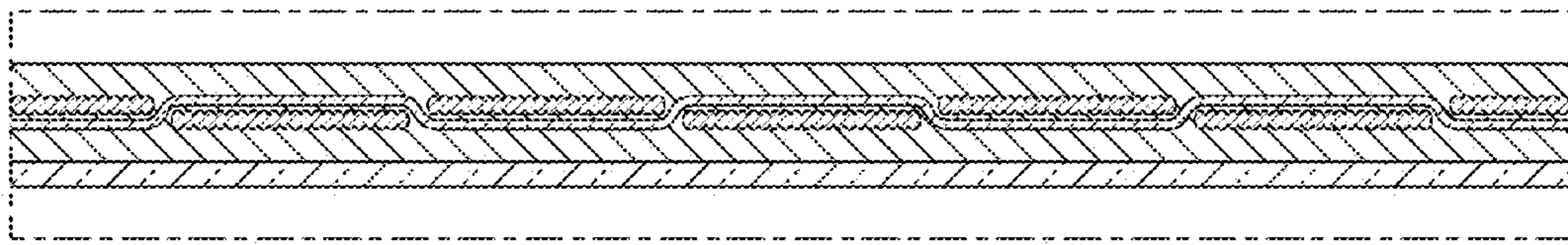


FIG. 9